

D20N10E

20 Amps, 95Volts N-CHANNEL Power MOSFET

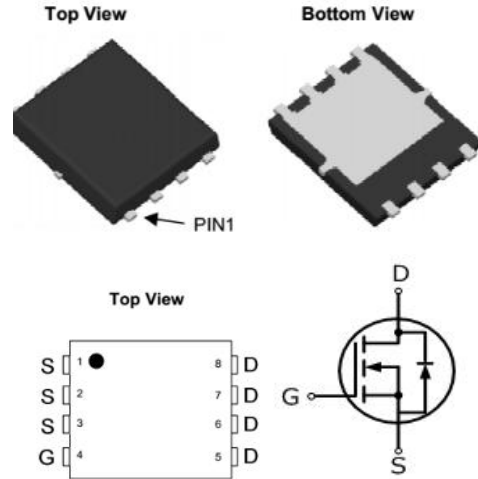
FEATURE

- 20A,95V, $R_{DS(ON)MAX}=7m\Omega$ $V_{GS}=10V/5A$
- Low gate charge
- Low C_{iss}
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

APPLICATION

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- LCD/LED back light

DFN5*6



GENERAL DESCRIPTION

The D20N10E is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent R_{DS(on)} and gate charge for most of the synchronous buck converter applications.

The D20N10E meet the RoHS and Green product requirement,100% EAS guaranteed with full function reliability approved.

Absolute Maximum Ratings ($T_C=25^{\circ}C$, unless otherwise noted)

Parameter	Symbol	D20N10E	UNIT
Drain-Source Voltage	V_{DSS}	95	V
Gate-Source Voltage	V_{GSS}	± 20	
Continuous Drain Current	I_D	20	A
Pulsed Drain Current(Note 1)	I_{DM}	80	
Single Pulse Avalanche Energy (Note 2)	E_{AS}	20	mJ
Avalanche Current	I_{AS}	20	A
Reverse Diode dv/dt (Note 3)	dv/dt	5.5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^{\circ}C$
Channel Temperature	T_{CH}	150	$^{\circ}C$
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	T_L	260	$^{\circ}C$

Thermal Characteristics

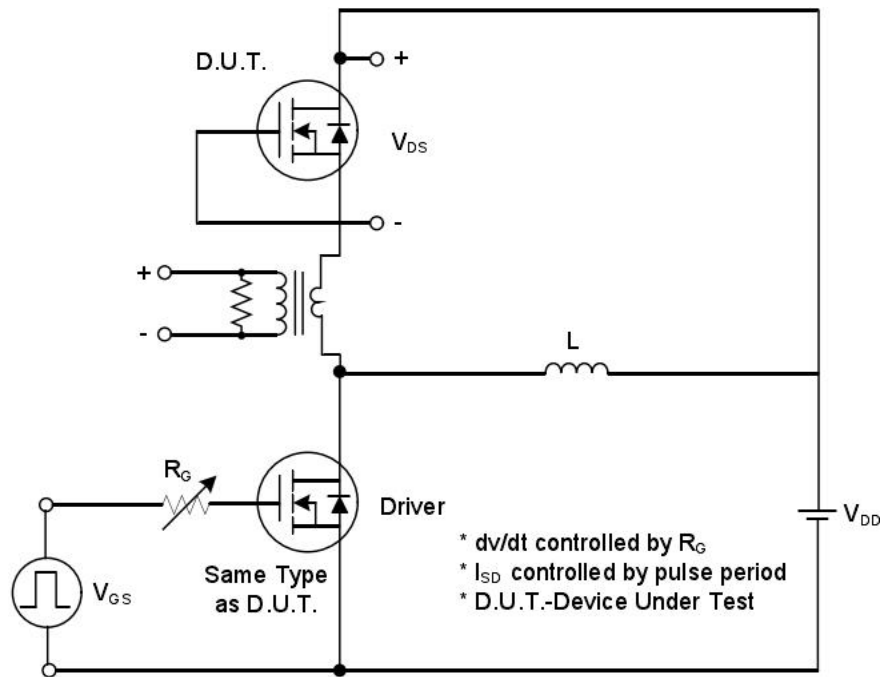
Parameter	Symbol	MAX	Units
Thermal resistance , Channel to Case	$R_{th(ch-c)}$	2.7	$^{\circ}C/W$
Thermal resistance , Channel to Ambient	$R_{th(ch-a)}$	55	$^{\circ}C/W$
Maximum Power Dissipation	$T_C=25^{\circ}C$ P_D	38	W

Electrical Characteristics ($T_c=25^\circ\text{C}$, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	95	—	—	V
Breakdown Temperature Coefficient	$\Delta BV_{DSS} / \Delta T_J$	Reference to 25°C , $I_D=250\mu A$	—	0.06	—	$V/^\circ\text{C}$
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=90V, V_{GS}=0V$	—	—	1	μA
	I_{DSS}	$V_{DS}=90V, V_{GS}=0V$ ($T_J = 55^\circ\text{C}$)	—	—	5	μA
Gate-Body Leakage Current, Forward	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	—	—	± 100	nA
On Characteristics						
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS}=10V, I_D=250\mu A$	2.0	—	4.0	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=5A$	—	5.2	7	m Ω
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=50V, V_{GS}=0V,$ $f=1.0\text{MHZ}$	—	2020	—	pF
Output Capacitance	C_{oss}		—	450	—	pF
Reverse Transfer Capacitance	C_{rss}		—	260	—	pF
Switching Characteristics						
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=50V, I_D=1A,$ $R_G=6.8\Omega, V_{GS}=10V$ $R_L=25\Omega$, (Note4,5)	—	25	—	ns
Turn-On Rise Time	t_r		—	18.5	—	ns
Turn-Off Delay Time	$t_{d(off)}$		—	58	—	ns
Turn-Off Fall Time	t_f		—	75	—	ns
Total Gate Charge	Q_g	$V_{DS}=50V, I_D=6A,$ $V_{GS}=10V$, (Note4,5)	—	50	—	nC
Gate-Source Charge	Q_{gs}		—	13	—	nC
Gate-Drain Charge	Q_{gd}		—	11	—	nC
Drain-Source Body Diode Characteristics and Maximum Ratings						
Continuous Diode Forward Current	I_S	$V_G = V_D = 0V$, Force Current	—	—	20	A
Pulsed Diode Forward Current	I_{SM}		—	—	80	A
Diode Forward Voltage	V_{SD}	$I_S=1A, V_{GS}=0V$	—	—	1.0	V

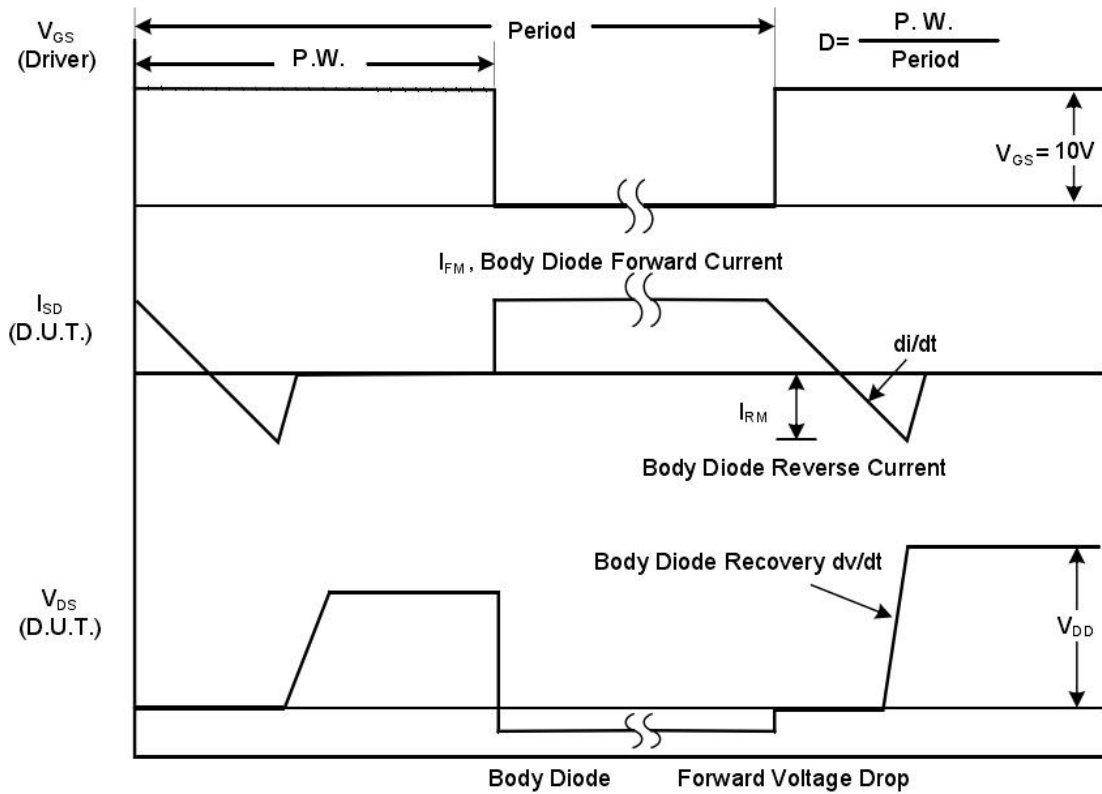
Notes

1. Repetitive Rating: pulse width limited by maximum junction temperature.
2. $V_{DD}=25V, L=0.1\text{mH}, R_g=25\Omega, I_{AS}=20A$, starting $T_J=25^\circ\text{C}$.
3. $I_{SD} \leq I_D, dI/dt=200A/\mu s, V_{DD} \leq BV_{DSS}$, starting $T_J=25^\circ\text{C}$, Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.
4. Repetitive rating; pulse width limited by maximum junction temperature.

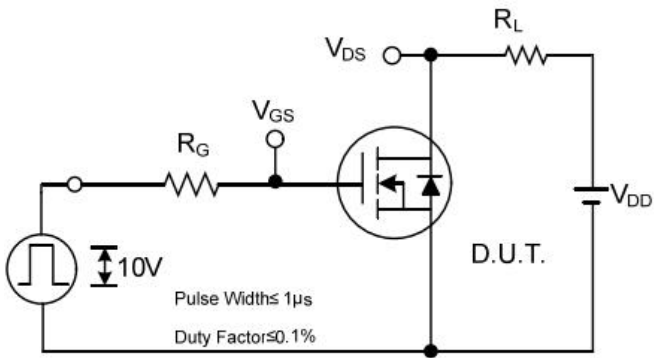
RATING AND CHARACTERISTIC CURVES



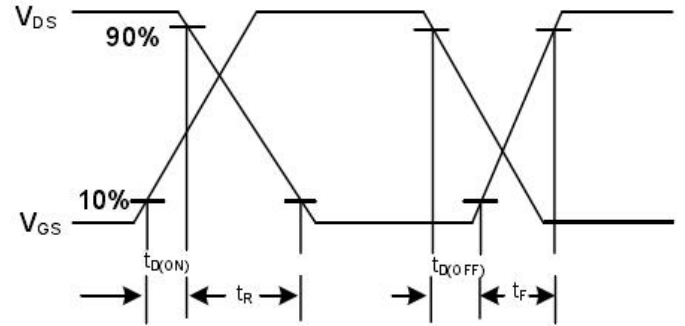
Peak Diode Recovery dv/dt Test Circuit



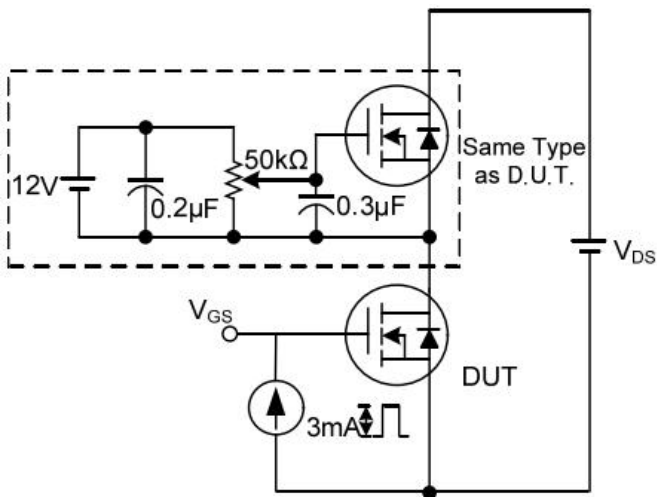
Peak Diode Recovery dv/dt Waveforms



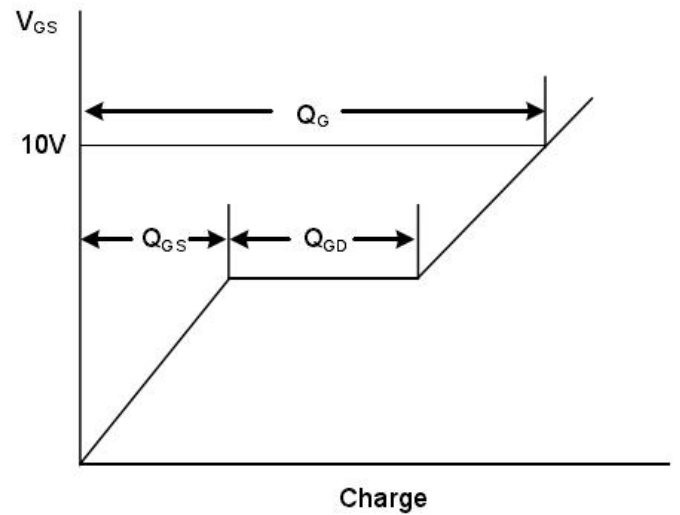
Switching Test Circuit



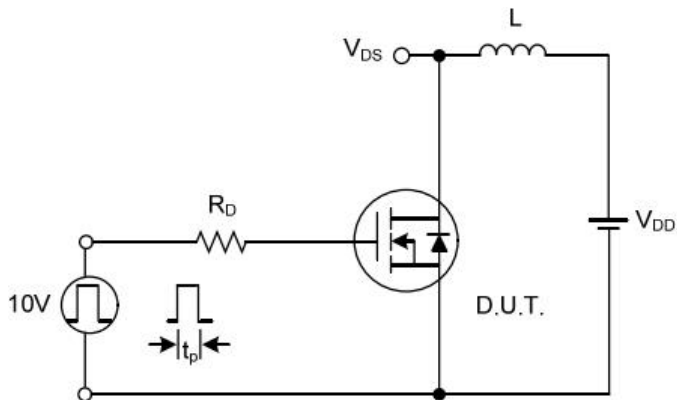
Switching Waveforms



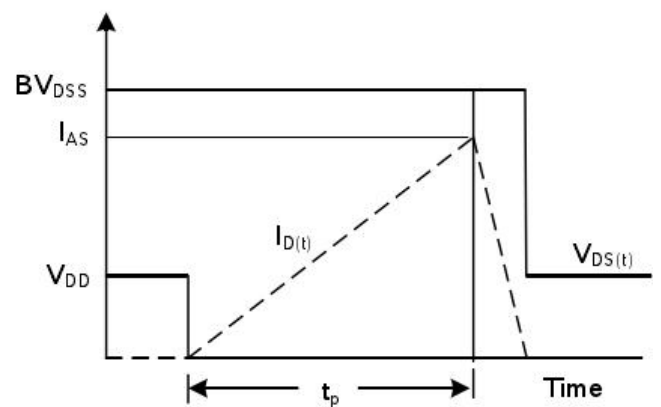
Gate Charge Test Circuit



Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms

RATING AND CHARACTERISTIC CURVES

